TELEFUNKEN Semiconductors

Infrared Driver

Description

The U426B is an IR-driver-IC for IR data communication. The circuit contains a programmable constant current source (DRV) to drive the IRED. The current is programmed by an external resistor (RS). With

the internal comparator (COMP) an external voltage can be monitored. The low power standby mode, controlled by means of the WAKE input, makes the circuit well suited for battery powered systems.

Features

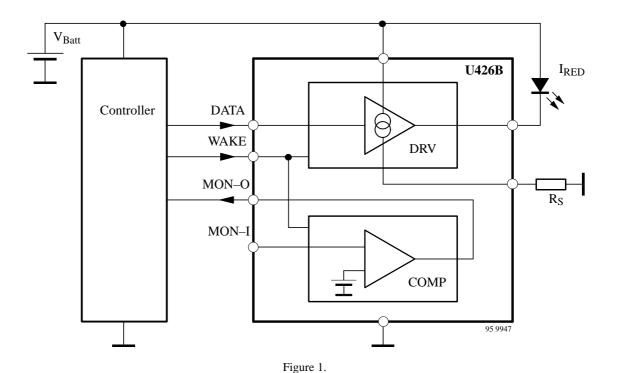
- Programmable constant current 200 mA to 1.2 A
- Signal frequency up to 500 kHz
- Low power standby mode
- Internal voltage comparator

Rev. A1: 20.06.1995

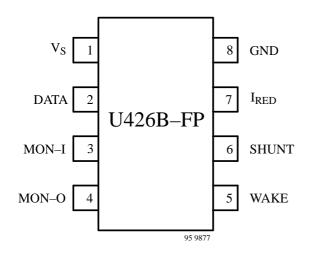
• Wide voltage range 2.4 to 12 V

Applications

- Keyless entry systems
- Remote control
- Wireless data communication



Pin Description



Pin	Symbol	Function
1	V_{S}	Supply voltage
8	GND	Circuit ground
2	DATA	Data input for switching the IRED output current on and off
7	IRED	IR-LED output, when the data input is high this output supplies the IR-LED with the constant current
6	SHUNT	The resistor at this pin adjusts the IRED output current
3	MON-I	Voltage monitor input of the internal comparator
4	MON-O	Voltage monitor output. This open collector output is active when the voltage at MON-I is below the internal reference $V_3 = 525 \text{ mV}$ typ.
5	WAKE	WAKE input. When LOW the circuit is in standby mode. A high level activates the circuit

Block Diagram

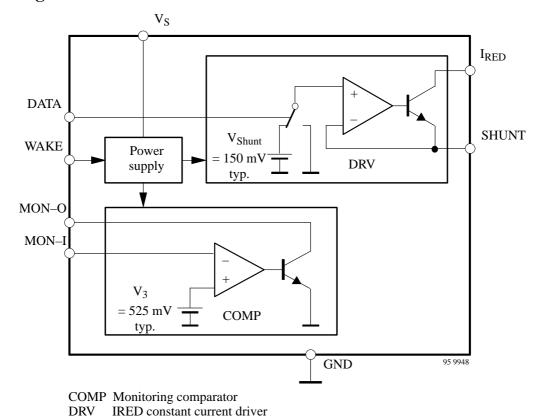


Figure 2.

Constant Current Driver (DRV)

The constant current driver converts the incoming data pulses into adequate constant current pulses. A high level applied to the data-input causes a constant current flow through the IR-diode connected to the IRED output. This current can be programmed via the external resistor (RS). To calculate the output current, use the following formula:

$$I_{RED} = 150 \frac{mV}{R_S}$$

Power Supply

The power supply circuit generates the internal supply voltage from an external voltage ($V_S = 2.4$ to 12 V). The V_S -pin is protected by an internal suppressor diode

against voltages above 13 V. The internal supply voltage can be switched on/off with a high/low-level at the WAKE input. Setting WAKE to low level switches the circuit from busy to standby mode, which results in a very low, current consumption (2 μA). Every change between busy and standby mode needs a latency up to 1 ms. Data transmission and voltage monitoring only takes place while WAKE remains high.

Monitoring Comparator (COMP)

The monitoring comparator compares the voltage at pin MON-I to an internal reference voltage of $V_3 = 525 \text{ mV}$ typ. The open collector output transistor is active, if the voltage at pin MON-I falls below the internal threshold voltage. The comparator can be used to monitor the power supply battery.

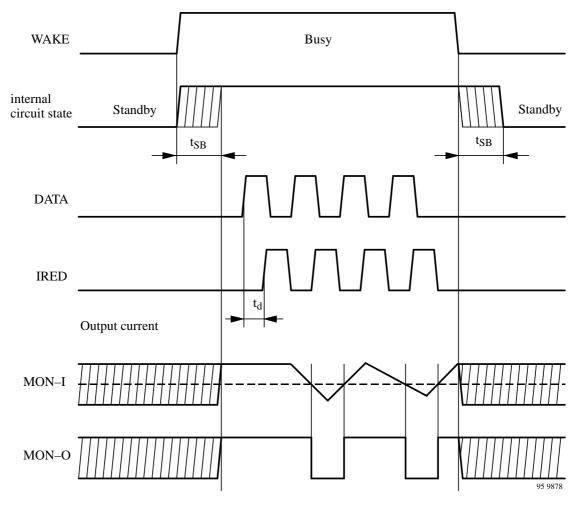


Figure 3. Timing diagram

Absolute Maximum Ratings

Parameters		Symbol	Value	Unit
Supply voltage	Pin 1	V_{S}	13.4	V
Supply current		I_{S}	40	mA
t < 10 μs		$i_{\rm S}$	150	mA
Input voltages	Pin 2, 3 and 5	$V_{\rm I}$	V_{S}	V
	Pin 6		1	V
Input currents	Pins 2, 3 and 5	I_{I}	1	mA
Output voltage	Pin 7	V_7	13.4	V
	Pin 4	V_4	V_{S}	V
Output current		I ₇	1.5	A
t < 100 μs	Pin 7	I_4	5	mA
	Pin 4			
Power dissipation				
$T_{amb} = 85^{\circ}C$				
SO 8: on p.c. board		P _{tot}	150	mW
on ceramic	P _{tot}	250	mW	
on ceramic with silicon grease		P _{tot}	430	mW
Junction temperature		Tj	125	°C
Ambient temperature range	T _{amb}	-40 to 85	°C	
Storage temperature range	T _{stg}	-40 to 150	°C	

Thermal Resistance

Parameters	Symbol	Value	Unit
Junction ambient			
SO 8: on p.c. board	R_{thJA}	220	K/W
on ceramic	R_{thJA}	140	K/W
on ceramic with silicon grease	R_{thJA}	80	K/W

Electrical Characteristics

 $V_S = 6$ V, $T_{amb} = 25$ °C, reference point pin 8, unless otherwise specified

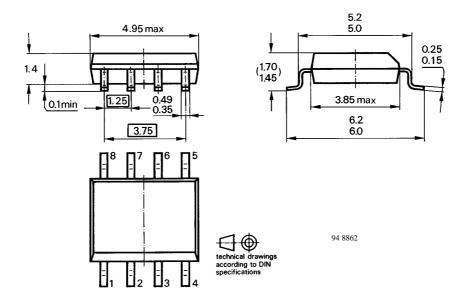
Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply current Pin 1						
Supply voltage	Pin 1	V_{S}	2.4		12	V
Standby current		I_{I}			2	μA
Wake-up current	Without pulse	I_{I}			1.5	mA
Overvoltage protection	$I_1 = 20 \text{ mA}$	V_{S}		13		V
DATA Pin 2						
Input signal	High	V_2	3	3.6	4.2	V
	Low	V_2	1.6	2.1	2.6	V
Common mode input			0		V_{S}	V
Rise time		t _r			500	ns
Fall time		t_{f}			500	ns
Signal frequency		f			500	kHz
Input current		I ₂			100	μΑ

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Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
MON-I Pin 3						
Input current	$V_3 = 6 \text{ V}$	I_3			0.3	μΑ
Reverse current	$V_3 = 0 V$	I _r			0.8	μΑ
Input voltage high	MON-I on	V_3	485	525	555	mV
Input voltage low	MON-O off	V_3	515	545	580	mV
Hysteresis				4		%
Temperature coefficient		TC		100		μA/K
MON-O	Pin 4					
Output current	$V_4 \ge 200 \text{ mV}$	I_4	1			mA
Output current	$V_4 \ge 400 \text{ mV}$	I_4	3			mA
Reverse current	$V_4 \le 6 \text{ V}$	I _r			0.2	μΑ
Output voltage High					V_{S}	V
Saturation voltage	$I_4 = 1 \text{ mA}$	V _{sat}			200	mV
WAKE	Pin 5	•				•
Input current	$V_5 = 6 \text{ V}$	I ₅			80	μA
	$V_5 = 0 \text{ V}$	I_5			±0.2	μA
Input voltage High	Busy	V_5			V_{S}	V
Input voltage LOW	Standby	V_5	0		0.2	V
SHUNT	Pin 6	_				
Output current IRED	$V_S = 2.4 \text{ V}; R_S = 0.62 \Omega$	I_7	205		245	mA
	$V_S = 6.0 \text{ V}; R_S = 0.62 \Omega$	I ₇	220		265	mA
	$V_S = 12 \text{ V}; R_S = 0.62 \Omega$	I ₇	235		275	mA
	$V_S = 6 \text{ V}; R_S = 0.11 \Omega$	I ₇	1.25 1.3		1.5 1.55	A
Chunt waltage	$V_S = 12 \text{ V}; R_S = 0.11 \Omega$ $V_2 = V_S = 6 \text{ V};$	I ₇	1.3	150		A
Shunt voltage	$\mathbf{V}_2 = \mathbf{V}_S = \mathbf{o} \mathbf{V};$ $\mathbf{R}_S = 0.11 \Omega$	V_{Shunt}	140	150	160	mV
Temperature coefficient	$T_{amb} = -40 \text{ to } 85^{\circ}\text{C}$	T _C		40		μV/K
IRED	Pin 7	10		70		μν/ΙΧ
Output voltage Output voltage	$V_2 = V_S = 6 \text{ V}; I_7 = 1 \text{ A}$ $V_2 = 0 \text{ V}; I_7 = 0$	V _{out}		12	13.2	mV V
Reverse current	$V_2 = 0 \text{ V}; I_7 = 0$ $V_2 = 0 \text{ V}; V_7 = 6 \text{ V}$	V _{out}		12	13.2	
Reverse current Rise/Fall time	$\mathbf{v}_2 - \mathbf{v} \ \mathbf{v}, \ \mathbf{v}_7 = \mathbf{v} \ \mathbf{v}$	I _r		-	300	μA
	Din 2 to nin 7	t _r			1	ns
Delay time	Pin 2 to pin 7	t _d				μs
Standby/Busy		t _{SB}			1	ms
Busy/Standby		t_{BS}		<u> </u>	1	ms

Dimensions in mm

Package: SO 8



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Ozone Depleting Substances Policy Statement

It is the policy of TEMIC TELEFUNKEN microelectronic GmbH to

- 1. Meet all present and future national and international statutory requirements.
- Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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